

Title (en)  
REINFORCEMENT MATERIAL AND REINFORCEMENT STRUCTURE OF STRUCTURE AND METHOD OF DESIGNING REINFORCEMENT MATERIAL

Title (de)  
VERSTÄRKUNGSMATERIAL UND VERSTÄRKUNGSKONSTRUKTION FÜR KONSTRUKTION UND VERFAHREN ZUM KONSTRUIEREN VON VERSTÄRKUNGSMATERIAL

Title (fr)  
MATERIAU D'ARMATURE ET STRUCTURE D'ARMATURE D'UNE STRUCTURE ET PROCEDE DE CONCEPTION D'UN MATERIAU D'ARMATURE

Publication  
**EP 1437459 A1 20040714 (EN)**

Application  
**EP 02775228 A 20020925**

Priority  
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• JP 0202167 W 20020308

Abstract (en)  
A reinforcement material has a woven body, a tape body, or a sheet body having high extendibility and high flexibility added thereto by weaving and installed on the surface of or inside the member or the boundary part of the member of the structure to reinforce the member, wherein the woven body, tape body, or sheet body has a Young's modulus equal to or lower than that of the member and a tensile breaking strain of 10% or higher, the Young's modulus of the reinforcement material should desirably be 1/2 to 1/20, particularly, 1/5 to 1/10 of that of the member, and specifically the value of the Young's modulus of the woven body should desirably be 500 to 50,000 Mpa, particularly, 1000 to 10,000 Mpa; the reinforcement structure wherein the member of the structure is reinforced by using the reinforcement material. An independent claim is also included for a method of designing reinforcement material.

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IPC 8 full level  
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